

## Application Data Sheet

### Application Information

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Method And Structure To Reduce  
Risk Of Gold Embrittlement In Solder  
Joints  
Attorney Docket Number:: TI-36327 (1962-08300)  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 1  
Total Drawing Sheets:: 2  
Small Entity?:: No

### Applicant Information

Applicant Authority type:: Inventor  
Primary Citizenship Country:: P.R. China  
Status:: Full Capacity  
Given Name:: Kejun  
Family Name:: ZENG  
City of Residence:: Coppell  
State or Province of Residence:: TX  
Country of Residence:: US  
Street of mailing address:: 204 Bricknell Lane  
City of mailing address:: Coppell  
State or Province of  
mailing address:: TX  
Country of mailing address:: US  
Postal or Zip Code of  
mailing address:: 75019

**Correspondence Information**

Correspondence Customer Number:: 23494

**Representative Information**

Representative Customer Number:: 23494

**Assignee Information**

Assignee name:: Texas Instruments Incorporated  
Street of mailing address:: P.O. Box 655474, MS 3999  
City of mailing address:: Dallas  
State or Province of  
mailing address:: TX  
Country of mailing  
address:: US  
Postal or Zip Code of  
mailing address:: 75265